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Serial Number: 10705579

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 **PALM INTRANET**

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US 20050181598 A1	20050818	Methods of providing an adhesion layer for adhesion of barrier and/or seed layers to dielectric films	438/654	438/627; 438/628; 438/652; 438/653; 438/677; 438/687	Kailasam, Sridhar K.
US 20050098440 A1	20050512	Methods for the electrochemical deposition of copper onto a barrier layer of a work piece	205/183	205/186; 205/187; 205/291	Kailasam, Sridhar K. et al.
US 20040231996 A1	20041125	Electroplating using DC current interruption and variable rotation rate	205/137	205/143	Webb, Eric G. et al.
US 20040136681 A1	20040715	Erbium-doped oxide glass	385/142	385/129	Drewery, John S. et al.
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US 20020148182 A1	20021017	Wooden floor truss and foundation wall assembly	52/299	52/292	Webb, Eric
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US 4897716 A	19900130	Method and apparatus for adaptively displaying video signals	348/452	348/474	Drewery; John O. et al.
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US 4322739 A	19820330	Processing of N.T.S.C. color television signals	348/392.1		Drewery; John O. et al.
US 4296434 A	19811020	Method of and apparatus for movement portrayal with a raster e.g. television, display	348/579	348/582	Drewery; John O. et al.
US 4288810 A	19810908	Method of and apparatus for deriving a PAL color television signal corresponding to any desired field in an 8-field PAL sequence from one stored field or picture of a PAL signal	348/662	348/453; 348/654	Drewery; John O. et al.
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US 4194219 A	19800318	Noise reduction in electrical signals	348/620		Drewery; John O.
US 4058836 A	19771115	Noise reduction in television signals	348/620	348/701	Drewery; John Oliver et al.